

PATENT ABSTRACTS OF JAPAN

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(71)Applicant : HITACHI CHEM CO LTD

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(72)Inventor : SAKURADA TAKASHI

(54) CERIUM OXIDE ABRASIVE AGENT, AND GRINDING METHOD OF BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a cerium abrasive agent which is small in sedimentation, easy in uniformity by stirring, and capable of grinding a surface to be ground of a silicon oxide insulating film at a high grinding speed without any damages while keeping the high flatness, and a board grinding method which is excellent in workability, and capable of grinding the surface to be ground of the silicon oxide insulating film at a high grinding speed without any damages while keeping the high flatness.

SOLUTION: The cerium oxide abrasive agent contains cerium oxide particles, and consists of the slurry of 1 $\mu\text{m/s}$ in maximum sedimentation velocity, and the predetermined board is ground using this cerium oxide abrasive agent.

LEGAL STATUS

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